

Xeon 1 Power Infrared Emitter LED

OSI3XNE1E1E

VER C.2

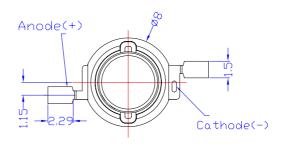
■Features

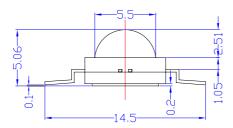
- · Highest luminous flux
- Super energy efficiency
- Very long operating life
- Superior ESD protection

Applications

- · Night Vision
- Camera
- Outdoor./Indoor applications

■Outline Dimension





(Ta=25)



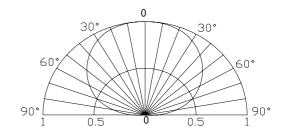
Unit:mm

Tolerance:±0.30mm

■Absolute Maximum Rating

Item	Symbol	Value	Unit
DC Forward Current	I_F	1000	mA
Pulse Forward Current*	I_{FP}	2000	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_{D}	1700	mW
Operating Temperature	Topr	- 30 ∼ +85	
Storage Temperature	Tstg	-40∼ +100	
Lead Soldering Temperature	Tsol	260 /5sec	-

■Directivity

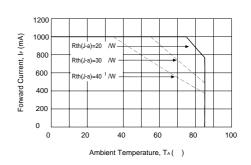


■Electrical -Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
DC Forward Voltage	V_{F}	I _F =350mA	-	1.5	1.7	V
DC Reverse Current	I_R	V _R =5V	-	-	10	μА
Peak Wavelength	λ_{P}	I _F =350mA	-	850	-	nm
Radiant Power	P_{O}	I _F =350mA	110	-	-	mW
50% Power Angle	2θ1/2	I _F =350mA	-	140	-	deg

(Ta=25)

Forward Operating Current (DC)



Note: Advises please attach heat sink to use if Power Dissipation is more than 0.5W.











^{*}Pulse width Max.10ms Duty ratio max 1/10



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■ Soldering Heat Reliability:

Reflow soldering Profile

- · Reflow soldering should not be done more than two times.
- · When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,

characteristics of the LEDs will or will not be damaged by repairing.

Solder		
Average ramp-up rate = 3° C/sec. max.		
Preheat temperature: 150°~180°C		
Preheat time = 120 sec. max.		
Ramp-down rate = 6° C/sec. max.		
Peak temperature = 220°C max.		
Time within 3°C of actual		
peak temperature = 25 sec. max.		
Duration above 200°C is 40 sec. max.		

